MATERIAL DECLARATION SHEET

BOURNS®

Package Type	PTVS10-xxxC-M		
Product Line	Semiconductor products		
Compliance Date	December 18, 2018		
RoHS Compliant	Yes	MSL	Level 1

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	1.90003	Amorphous Silica	60676-86-0	89.50	36.3639	40.63
				Solid Epoxy Resin 1	Proprietary	3.20	1.3002	
				Solid Epoxy Resin 2	Proprietary	2.40	0.9751	
				Phenol Resin	Proprietary	4.10	1.6658	
				Crystalline Silica	14808-60-7	0.50	0.2031	
				Carbon Black	1333-86-4	0.30	0.1219	
2	Leadframe	Copper Alloy	0.5920	Copper	7440-50-8	97.44	12.3359	12.66
				Iron	7439-89-6	2.35	0.2975	
				Other, not to declare	-	0.21	0.0266	
3	Electrodes	Copper Alloy	1.493	Copper	7440-50-8	99.50	31.7604	31.92
				Other, not to declare	-	0.50	0.1596	
4	Clip	Copper Alloy	0.1181	Copper	7440-50-8	99.50	2.5173	2.53
				Other, not to declare	-	0.50	0.0127	
5	Chip	Silicon	0.3032	Silicon	7440-21-3	89.01	5.7678	6.48
				Aluminum	7429-90-5	4.19	0.2715	
				Nickel	7440-02-0	6.49	0.4206	
				Gold	7440-57-5	0.31	0.0201	
6	Die Attach	Solder	0.2493	Lead*	7439-92-1	92.50	4.9302	5.33
				Tin	7440-31-5	5.00	0.2665	
				Silver	7440-22-4	2.50	0.1333	
7	Terminal Finish	Tin	0.0212	Tin	7440-31-5	100.00	0.45	0.45
		Total Weight	4.67683					

*** 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)**

CASRN: CAS Registry Number® is a Registered Trademark of the American Chemical Society